ASSOCIATION CONNECT ELECTRONICS INDUST	© Copyright 2005, IPC, E	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		^ · ·				Type * Declaration Class * Oute Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information									
Supplier Info	rmation														
Company name* Company			ompany uni	ompany unique ID			Unique ID Authority					Response Date*			
nsemi											2023-06-	2023-06-08			
Contact Name		Ti	itle - Contac	e - Contact			Phone - Contact*				Email - 0	Email - Contact*			
Product-Env-Ste	wards	Pr	Product Enviro Compliance]	NA				Product	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title				Title - Representative			Phone - Representative*				Email - 1	Email - Representative*			
Product-Env-Ste	wards	Pr	Product Enviro Compliance			1	NA				Product	Product-Env-Stewards@onsemi.com			
Reque	4		em Number Mfr Item Name 584BDTR2G LOG CMOS HEX SCHMIT				Effective Date	Version	Manufacturing Site		V	Veight*	UOM	Unit Type	
						RIG	2023-06-08 PH		PH1		1.764	mg	Each		
Ianufacturin	g Proccess Information														
Termin	Terminal Plating / Grid Array Material		Terminal Base Alloy J		J-STD-020 MS	L Rating	Peak Process Body Temperature		perature	e Max Time at Peak Temperat		ure Number of Reflow Cycles			
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1		1		260	C	C 30		secono	seconds 3			
Comments												,			
vel 1 - maximun	n time at peak temperature di	uring solder	ring is 10-30	0 seconds											
or more informa	ation regarding material com	oosition plea	ase refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.476	mg	Supplier	Silicon (Si)	7440-21-3		1.476	mg
Die Attach	0.191	mg		Epoxy resin	proprietary data		0.0439	mg
			Supplier	Silver (Ag)	7440-22-4		0.1471	mg
Lead Frame	14.903	mg	Supplier	Silver (Ag)	7440-22-4		0.6796	mg
			Supplier	Magnesium (Mg)	7439-95-4		0.0209	mg
			Supplier	Silicon (Si)	7440-21-3		0.0924	mg
			В	Nickel (Ni)	7440-02-0		0.4262	mg
			Supplier	Copper (Cu)	7440-50-8		13.6839	mg
Mold Compound-Black	34.856	mg		Epoxy resin	proprietary data		1.7428	mg
			Supplier	Phenol Resin	Proprietary Data		1.3942	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.4856	mg
			Supplier	Carbon Black (C)	1333-86-4		0.3486	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		27.8848	mg
Plating	0.239	mg	Supplier	Tin (Sn)	7440-31-5		0.239	mg
Wire Bond	0.099	mg	Supplier	Palladium (Pd)	7440-05-3		0.002	mg
			Supplier	Copper (Cu)	7440-50-8		0.097	mg